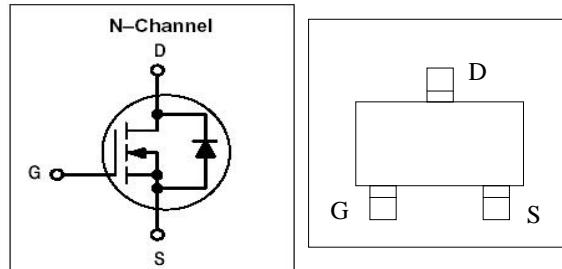
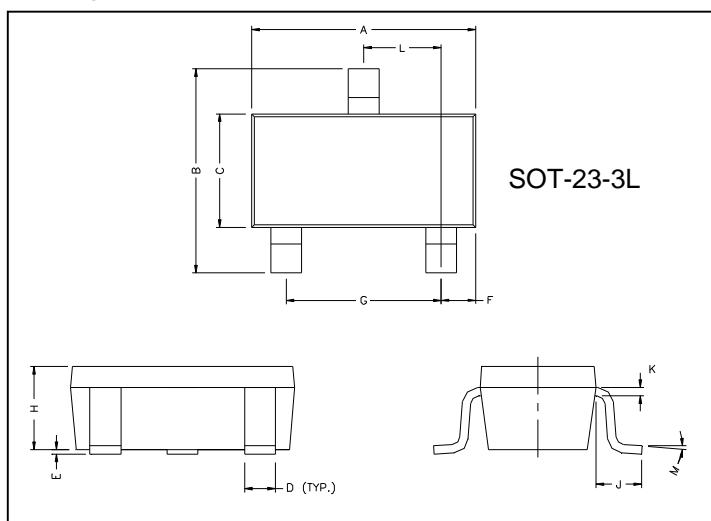


20V N-Channel Enhancement Mode MOSFET

FEATURE

- 20V/4.0A, $R_{DS(ON)} = 55\text{m}\Omega$
@ $VGS = 4.5\text{V}$
- 20V/3.4A, $R_{DS(ON)} = 70\text{m}\Omega$
@ $VGS = 2.5\text{V}$
- 20V/2.8A, $R_{DS(ON)} = 90\text{m}\Omega$
@ $VGS = 1.8\text{V}$

Package Dimensions



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	1.90	REF.
B	2.65	2.95	H	1.00	1.30
C	1.50	1.70	K	0.10	0.20
D	0.35	0.50	J	0.40	-
E	0	0.10	L	0.85	1.15
F	0.45	0.55	M	0°	10°

Maximum Ratings and Thermal Characteristics ($TA = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I_D	4.0	A
Pulsed Drain Current	I_{DM}	10	
Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	1.25	W
		0.8	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted)	$R_{\theta JA}$	105	°C/W

20V N-Channel Enhancement Mode MOSFET**ABSOULTE MAXIMUM RATINGS (Ta = 25 Unless otherwise noted)**

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V _{GSS}	+/-12	V
Continuous Drain Current (T _J =150)	T _A =25 T _A =70	I _D 4.0 3.4	A
Pulsed Drain Current	I _{DM}	10	A
Continuous Source Current (Diode Conduction)	I _S	1.6	A
Power Dissipation	T _A =25 T _A =70	P _D 1.25 0.8	W
Operation Junction Temperature	T _J	150	
Storage Temperature Range	T _{STG}	-55/150	
Thermal Resistance-Junction to Ambient	R _{JA}	105	/W

20V N-Channel Enhancement Mode MOSFET
ELECTRICAL CHARACTERISTICS (Ta = 25 °C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS	V _{GS} =0V, ID=-250uA	20			V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , ID=-250uA	0.4		1.0	V	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =+/-12V			100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V			1	uA	
		V _{DS} =-20V, V _{GS} =0V T _J =55			5		
On-State Drain Current	I _{D(on)}	V _{DS} = -5V, V _{GS} =-4.5V	6.0			A	
Drain-source On-Resistance	R _{DS(on)}	V _{GS} =4.5V, ID=4.0A		0.04	0.055		
		V _{GS} =2.5V, ID=3.4A		0.05	0.07		
		V _{GS} =1.8V, ID=2.8A		0.065	0.090		
Forward Transconductance	g _{fs}	V _{DS} =5V, ID=3.6V		10		S	
Diode Forward Voltage	V _{SD}	I _S =1.6A, V _{GS} =0V		0.8	1.2	V	
Dynamic							
Total Gate Charge	Q _g	V _{DS} =6V, V _{GS} =4.5V ID = 2.8A		4.8	8	nC	
Gate-Source Charge	Q _{gs}			1.0			
Gate-Drain Charge	Q _{gd}			1.0			
Input Capacitance	C _{iss}	V _{DS} =6V, V _{GS} =0V F=1MHz		485		pF	
Output Capacitance	C _{oss}			85			
Reverse Transfer Capacitance	C _{rss}			40			
Turn-On Time	t _{d(on)} t _r	V _{DD} =6V, R _L =6Ω ID=1A, V _{GEN} =4.5V R _G =6Ω		10	25	nS	
				13	60		
Turn-Off Time	t _{d(off)} t _f			18	70		
				15	60		

20V N-Channel Enhancement Mode MOSFET

TYPICAL CHARACTERISTICS (25 °C Unless noted)

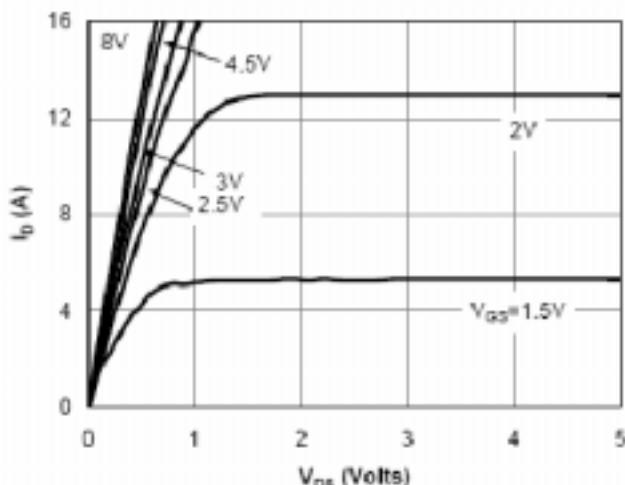


Fig 1: On-Region Characteristics

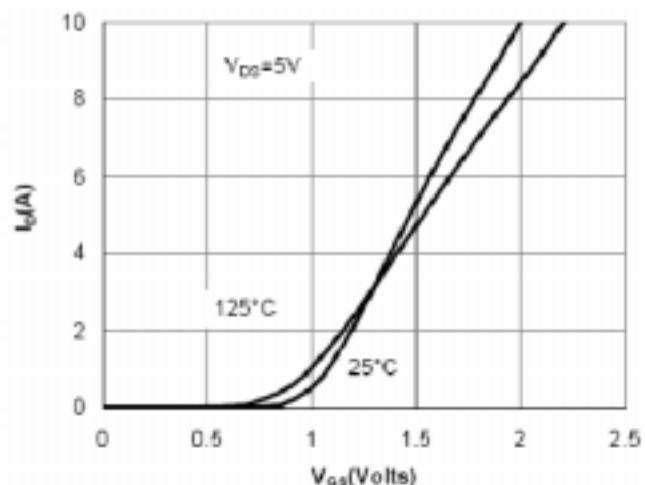


Figure 2: Transfer Characteristics

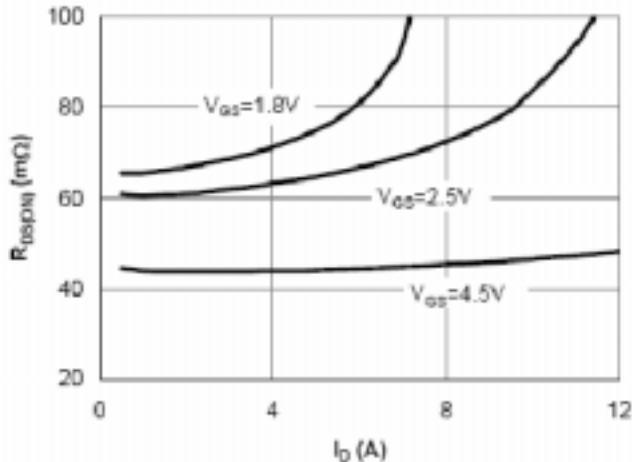


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

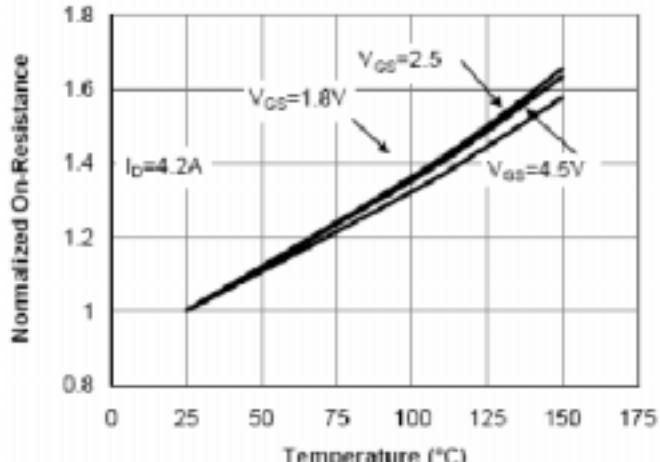


Figure 4: On-Resistance vs. Junction Temperature

20V N-Channel Enhancement Mode MOSFET

4.0A

TYPICAL CHARACTERISTICS (25 Unless noted)

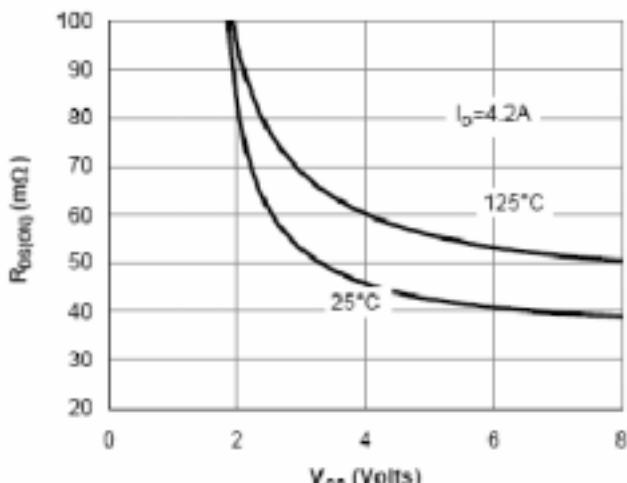


Figure 5: On-Resistance vs. Gate-Source Voltage

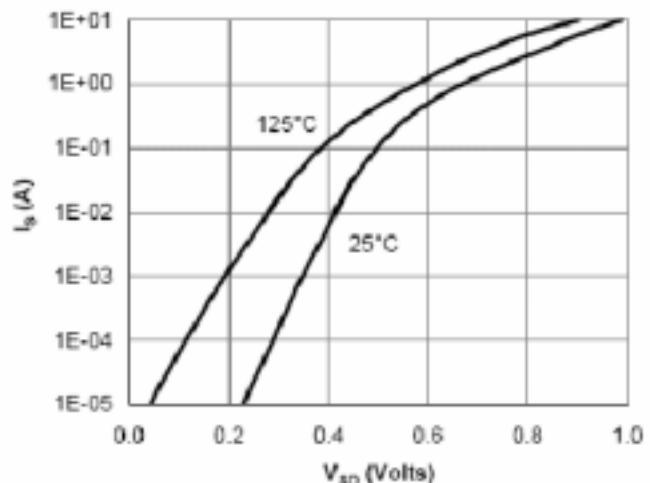


Figure 6: Body-Diode Characteristics

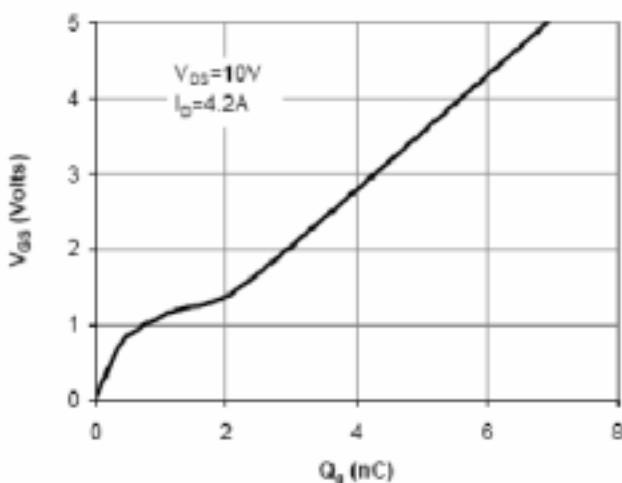


Figure 7: Gate-Charge Characteristics

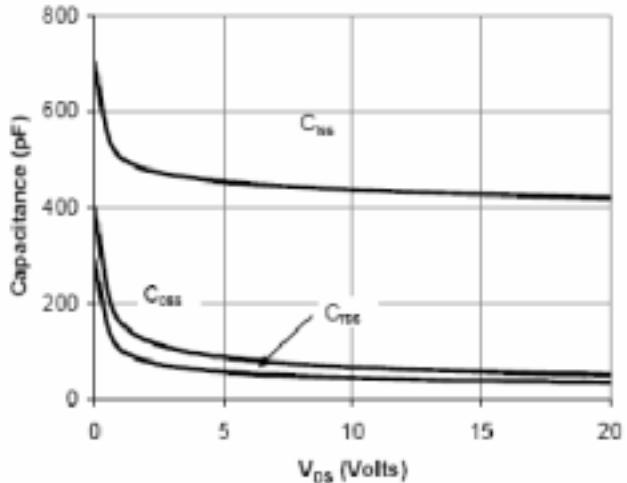


Figure 8: Capacitance Characteristics

20V N-Channel Enhancement Mode MOSFET

TYPICAL CHARACTERISTICS

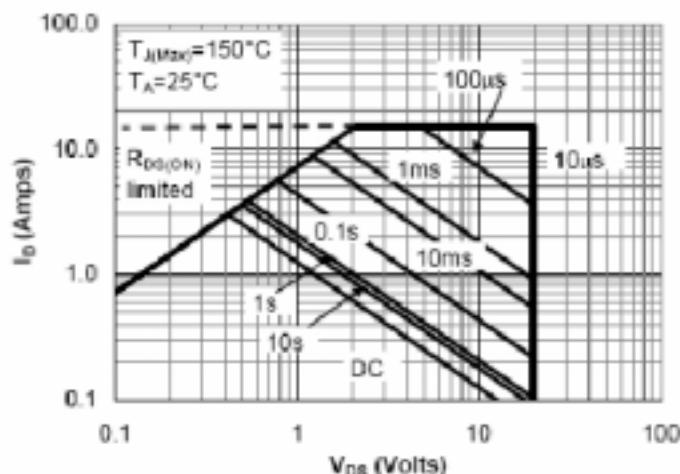


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

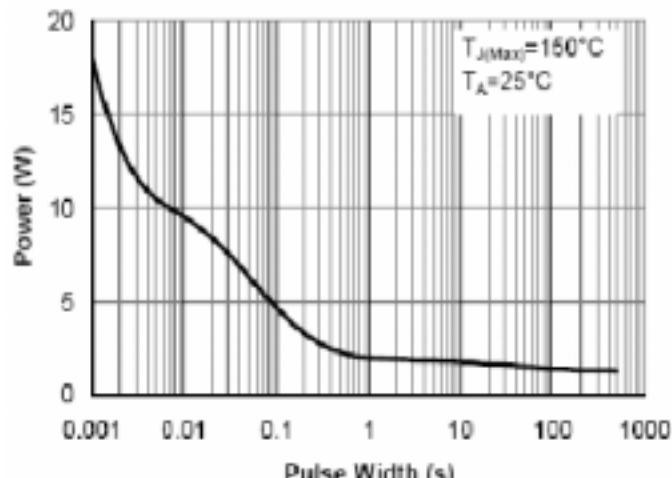


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

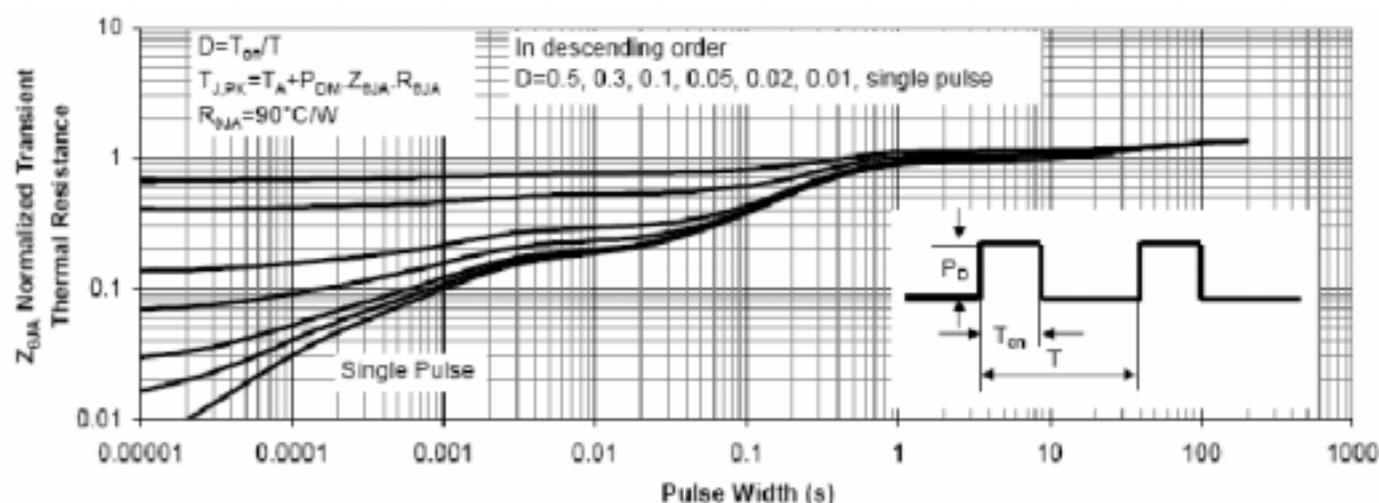


Figure 11: Normalized Maximum Transient Thermal Impedance